**Electrical Optical Characteristics at Ta=25℃**

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Test Condition |
|---|---|---|---|---|---|---|
| Radiant Intensity | Ie | 2.2 | 3.1 | 4.5 | mW/sr | $I_F$=20mA (Note 1,3) |
| Viewing Angle | 1/2 | --- | 85 | --- | deg | (Note 2) |
| Peak Wavelength | **S** | --- | 940 | --- | nm | $I_F$=20mA |
| Spectral Line Half- Width | Δ | --- | 50 | --- | nm | $I_F$=20mA |
| Forward Voltage | $V_F$ | --- | 1.22 | 1.5 | V | $I_F$=50mA |
| Reverse Current | $I_R$ | --- | --- | 100 | μA | $V_R$=8V |

**Note:**

1. Point sources of the amount of radiation per unit time in a given direction within the unit solid Angle radiated energy.

2. LVWKRII -axis angle at which the Radiant Intensity is half the axial Radiant Intensity.

3. The Ie guarantee should be added ±15% tolerance.

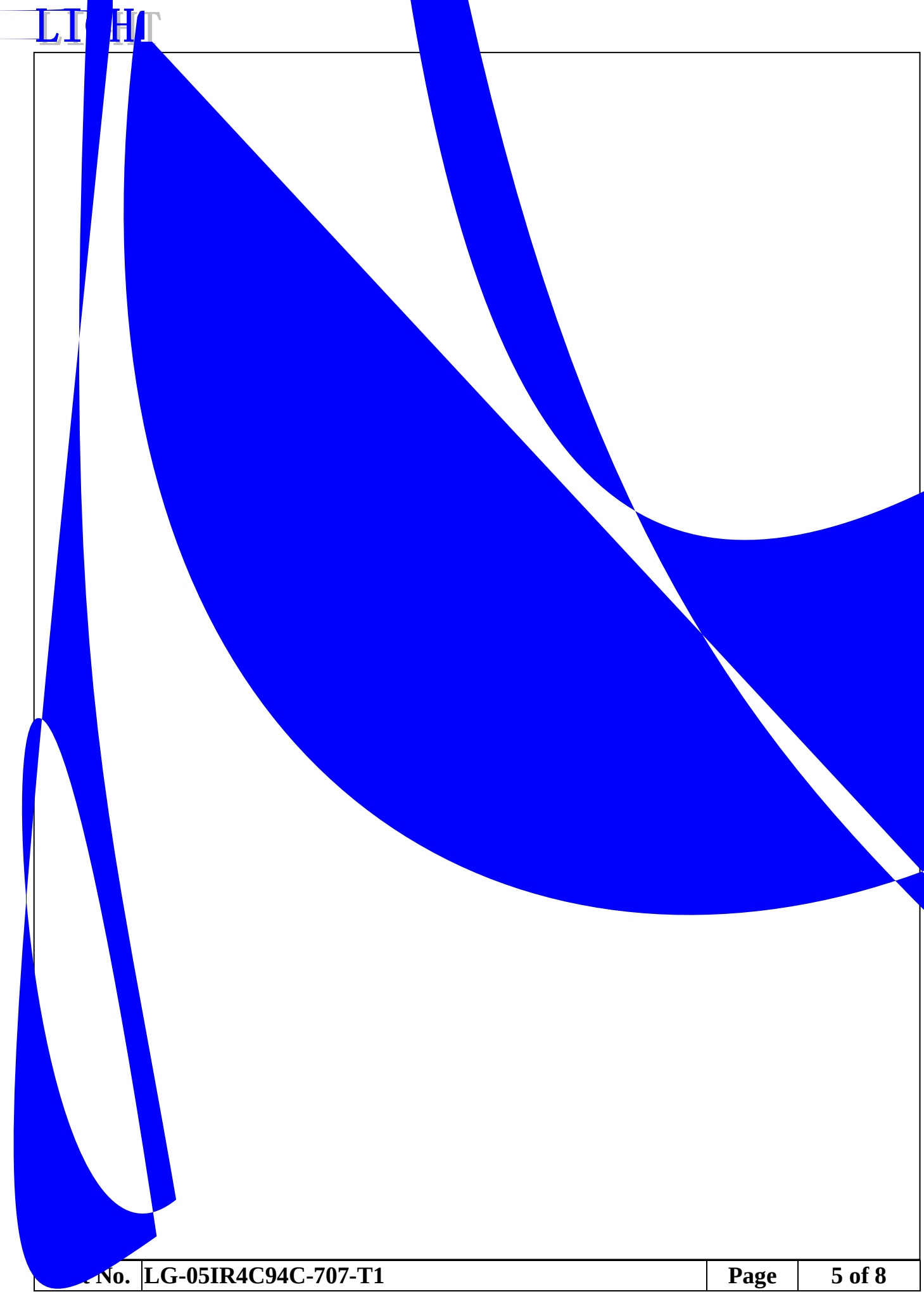
## Infrared Emitting Diode Specification

**●Commodity: Infrared emitting diode**

**●Intensity Bin Limits (At 20mA)**

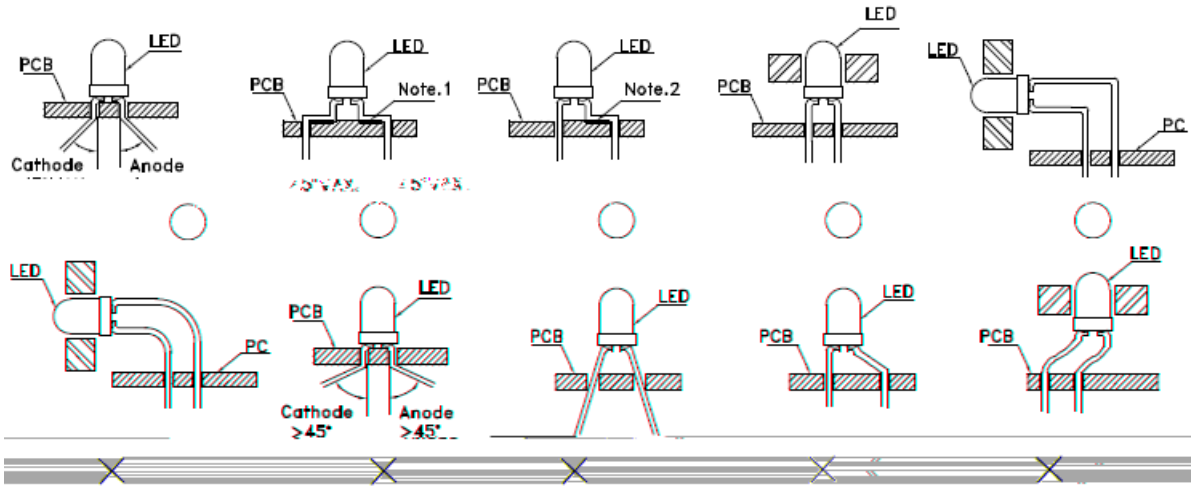
| BIN CODE | Min. (mW/sr) | Max. (mW/sr) |
|---|---|---|
| **1** | 2.2 | 2.6 |
| **2** | 2.6 | 3.1 |
| **3** | 3.1 | 3.7 |
| **4** | 3.7 | 4.5 |

**NOTE**: The Ie guarantee should be added ±15% tolerance.



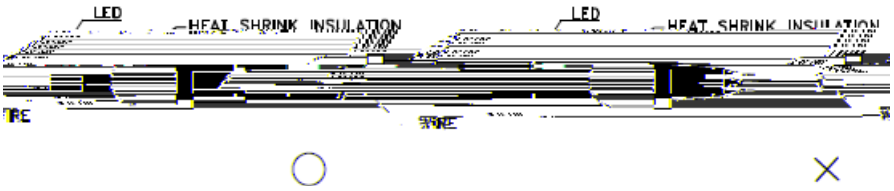
## LED MOUNTING METHOD

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.(Fig.1)




3RRUUHFWPRXQWLQJPHWKRG 1,QFRUUHFWPRXQWLQJPHWKRG 1RW-2: Do not route PCB Trace in the contact area between the leadframe and the PCB to prevent short-circuit.

2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit (Fig.2)




3. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.

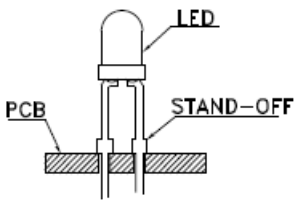



Fig. 3

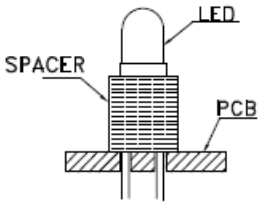



Fig. 4

LEAD FORMING PROCEDURES